

**REMARKS**

At the outset, the Examiner is thanked for the thorough review and consideration of the pending application. The Office Action dated October 4, 2007 has been received and its contents carefully reviewed.

Claims 9 and 12 have been amended. Claims 1-8 and 17-21 have been withdrawn from consideration as the result of the earlier restriction requirement. No new matter has been added. Claims 9-16 remain pending in this application. Applicant respectfully requests favorable reconsideration in view of the remarks presented herein below.

In the Office Action, claim 12 is objected to because of the following informalities: “the signal line includes a gate line and a data line” is unclear. Applicants have amended claim 12 to recite “the signal line includes a gate line or a data line,” as the Examiner suggested. Thus, Applicants respectfully request that the objection to claim 12 be withdrawn.

Claims 9-16 are rejected under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 6,432,755 to Sung et al. (“Sung”) in view of U.S. Patent No. 6,219,125 to Ishikura et al. (“Ishikura”). Applicants respectfully traverse the rejection as being based upon references that neither teach nor suggest the combination of features recited by independent claim 9, as amended, and hence dependent claims 10-16.

With respect to independent claim 9, as amended, Applicants respectfully submit that Sung and Ishikura fail to teach or suggest the claimed combination including at least a feature of “wherein a top surface of the copper layer has a narrower width than a top surface of the copper compound layer,” as recited by independent claim 9. The Office Action admits that Sung fails to teach forming a copper compound layer on a substrate, forming a copper layer on the copper compound layer and forming a signal line by etching the copper compound layer and the copper layer recited by independent claim 9. The Office Action relies upon Ishikura to remedy the

above-identified deficiencies of Sung. However, Applicants respectfully submit in Ishikura, a top surface of a principle electroconductive layer 12, as allegedly considered as a copper layer by the Examiner, has the same width as a top surface of an adhesive layer 11, as allegedly considered as a copper compound layer by the Examiner. Thus, Ishikura fails to teach the claimed combination including at least a feature of “wherein a top surface of the copper layer has a narrower width than a top surface of the copper compound layer,” as recited by independent claim 9, as amended.

For the above reasons, Applicant respectfully asserts that the rejections under 35 U.S.C. § 103(a) should be withdrawn because none of the applied prior art references, whether taken individually or in combination, teach or suggest the novel combination of features clearly recited by independent claim 9, and hence dependent claims 10-16.

Applicants believe the foregoing amendments and remarks place the application in condition for allowance and early, favorable action is respectfully solicited.

If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at (202) 496-7500 to discuss the steps necessary for placing the application in condition for allowance. All correspondence should continue to be sent to the below-listed address.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37

C.F.R. §1.136 for any necessary extension of time, or any other fees required to complete the filing of this response, may be charged to Deposit Account No. 50-0911. Please credit any overpayment to deposit Account No. 50-0911.

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Respectfully submitted,

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